

Ultra Low Capacitance ESD Protection Array

FEATURES

- Meet IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- Meet IEC61000-4-4 (EFT) rating. 40A (5/50ns)
- Protects two directional I/O lines
- Working voltage: 5V
- Low leakage, low operating and clamping voltage
- Ultra low capacitance
- Pb free version and RoHS compliant
- Packing code with suffix "G" means
- green compound (halogen-free)

MECHANICAL DATA

- Case: MSOP-08 small outline plastic package
- Terminal: Matte tin plated, lead free., solderable per MIL-STD-202, Method 208 guaranteed
- Molding Compound Flammability Rating: UL 94V-0
- High temperature soldering guaranteed : 260°C/10s
- Weight: 25 ± 0.5 mg
- Marking code: UC68M



MSOP-08





MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)			
PARAMETER	SYMBOL	VALUE	UNIT
Peak Pulse Power (tp=8/20µs waveform)	P _{PP}	200	W
Peak Pulse Current (tp=8/20µs)	I _{PP}	6	А
ESD per IEC 61000-4-2 (Air)	V _{ESD}	± 15	КV
ESD per IEC 61000-4-2 (Contact)	VESD	± 8	ΓV
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

PARAMETER		SYMBOL	MIN	MAX	UNIT
Reverse Stand-Off Voltage		V _{RWM}	-	5	V
Reverse Breakdown Voltage	I _R =1 mA	V _(BR)	6.5	-	V
Reverse Leakage Current	V _R = 5 V	I _R	-	0.5	μA
Clamping Voltage	I _{PP} = 1 A	N/	-	9.8	- V
	I _{PP} = 6 A	V _c	-	15	
Junction Capacitance	V _R =0 V , f = 1.0 MHz	CJ	C).5	pF



RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)



Fig. 3 Clamping Voltage VS. Peak Pulse Current











ORDER INFORMATION (EXAMPLE)

TESDM5V0A RMG



Green compound code Packing code Part no.

PACKAGE OUTLINE DIMENSIONS MSOP-08





DIM.	Unit (mm)		Unit (inch)	
ווש.	Min	Max	Min	Max
А	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.22	0.38	0.009	0.015
D	0.65	REF	0.025	6 REF
E	4.75	5.05	0.187	0.199
F	-	0.25	-	0.010
G	0.13	0.23	0.005	0.009
Н	0.40	0.66	0.016	0.026
I	0.75	0.95	0.030	0.037

SUGGEST PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)
	Тур.	Тур.
А	4.80	0.189
В	0.41	0.016
С	0.65	0.026
D	1.02	0.040

Note: 1. The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application.



APPLICATIONS INFORMATION

- Applications for Microprocess based equipment
- IEEE1394 Firewire Ports
- ATM Interfaces
- High Definition Multi-Media Interface(HDMI)
- Digital Video Interface (DVI)
- Video Graphs Cards
- Designed for protection of high-speed interfaces such as USB3.0
- Ultra low capacitance between the pairs while being rated to handle >±8kV, ESD contact discharges and >±15kV air discharge
- TESDM5V0A is ultra low capacitance ESD prototion array designed to protect high speed data interfaces. This series has been specifically designed to protect sensitive components which are connected to high-speed data and transmission lines form overvoltage caused by ESD, CDE (Cable Discharge Events), and EFT(electrical fast transients)



Pin	Definition
1, 2, 3, 4, 5, 6	I/O Lines
7	Ground
8	Vcc

TYPICAL APPLICATION

Schematic Diagram for USB 3.0 Protection





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